# UNITED STATES SECURITIES AND EXCHANGE COMMISSION WASHINGTON, DC 20549

### FORM 8-K

CURRENT REPORT
Pursuant to Section 13 or 15(d) of the
Securities Exchange Act of 1934

May 22, 2008 Date of report (Date of earliest event reported)

# TTM TECHNOLOGIES, INC.

(Exact Name of Registrant as Specified in Charter)

### DELAWARE

(State or other jurisdiction of incorporation)

0-31285	91-1033443
(Commission File Number)	(IRS Employer Identification Number)
SANTA ANA	RBOR BOULEVARD A, CALIFORNIA 12704
(Address of Principal Ex	xecutive Offices) (Zip Code)
· ,	327-3000 number, including area code)
k the appropriate box below if the Form 8-K filing is intended to simultaneously ral Instruction A.2. below):	satisfy the filing obligation of the registrant under any of the following provisions (see
Written communications pursuant to Rule 425 under the Securities Act (17 CF	TR 230.425)
Soliciting material pursuant to Rule 14a-12 under the Exchange Act (17 CFR	240.14a-12)
Pre-commencement communications pursuant to Rule 14d-2(b) under the Exc	hange Act (17 CFR 240.14d-2(b))
Pre-commencement communications pursuant to Rule 13e-4(c) under the Excl	hange Act (17 CFR 240.13e-4(c))

### Item 7.01. Regulation FD Disclosure.

The Company is furnishing this Report on Form 8-K pursuant to Regulation FD in connection with the disclosure of textual information from a slide show presentation given at the TTM Technologies 2008 Analyst Day on May 22, 2008.

The information in this Report on Form 8-K (including the exhibit) is furnished pursuant to Item 7.01 and shall not be deemed to be "filed" for the purpose of Section 18 of the Securities Exchange Act of 1934 or otherwise subject to the liabilities of that section. This Report will not be deemed an admission as to the materiality of any information in the report that is required to be disclosed solely by Regulation FD.

The Company does not have, and expressly disclaims, any obligation to release publicly any updates or any changes in the Company's expectations or any change in events, conditions, or circumstances on which any forward-looking statement is based.

The information included with this Report includes graphic images or slides used in the presentation. These slides will also be available for viewing at our website located at <a href="https://www.ttmtech.com">www.ttmtech.com</a>, although we reserve the right to discontinue that availability at any time.

The information in this Report includes references to "EBITDA." EBITDA means earnings before interest expense, income taxes, depreciation and amortization. We present EBITDA to enhance the understanding of our operating results. EBITDA is a key measure we use to evaluate our operations. In addition, we provide our EBITDA because we believe that investors and securities analysts will find EBITDA to be a useful measure for evaluating our operating performance and comparing our operating performance with that of similar companies that have different capital structures and for evaluating our ability to meet our future debt service, capital expenditures and working capital requirements. However, EBITDA should not be considered as an alternative to cash flows from operating activities as a measure of liquidity or as an alternative to net income as a measure of operating results in accordance with accounting principles generally accepted in the United States.

### Item 9.01. Financial Statements and Exhibits

- (a) Financial Statements of Business Acquired. Not applicable.
- (b) *Pro Forma Financial Information.* Not applicable.
- (c) Exhibits.
   Exhibit 99.1. Slides presented at the TTM Technologies 2008 Analyst Day on May 22, 2008.

### SIGNATURE

Pursuant to the requirements of the Securities Exchange Act of 1934, the registrant has duly caused this report to be signed on its behalf by the undersigned hereunto duly authorized.

TTM TECHNOLOGIES, INC.

Date: May 22, 2008 By: /s/ Steven W. Richards

Steven W. Richards Chief Financial Officer

# TTM Technologies, Inc.

2008 Analyst Day The Roosevelt Hotel Thursday, May 22, 2008



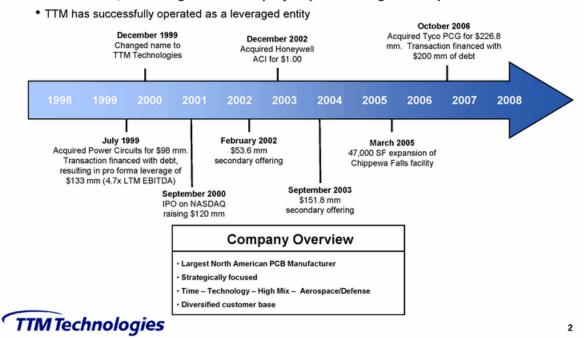
# TTM and Industry Overview

Kent Alder - Chief Executive Officer and President

This presentation contains forward-looking statements that relate to future events or performance. These statements reflect the company's current expectations, and the company does not undertake to update or revise these forward-looking statements, even if experience or future changes make it clear that any projected results expressed or implied in this or other company statements will not be realized. Furthermore, readers are cautioned that these statements involve risks and uncertainties, many of which are beyond the company's control, which could cause actual results to differ materially from the forward-looking statements. These risks and uncertainties include, but are not limited to, the company's dependence upon the electronics industry, the company's dependence upon a small number of customers, general economic conditions and specific conditions in the markets TTM addresses, the unpredictability of and potential fluctuation in future revenues and operating results, increased competition from low-cost foreign manufacturers, and other "Risk Factors" set forth in the company's most recent SEC filings.

# **Company Overview**

Incorporated in 1998, TTM has a proven track record of executing successful transactions, including debt and equity capital raising and acquisitions



# **Facility Footprint**

The facility footprint enables TTM to continue to execute its facility specialization strategy





# **PCB Market Forecast**

The \$47.9 billion global PCB market is projected to grow at 5.0% through 2012

The \$4.7 billion Americas PCB segment represents approximately 10% of the global market







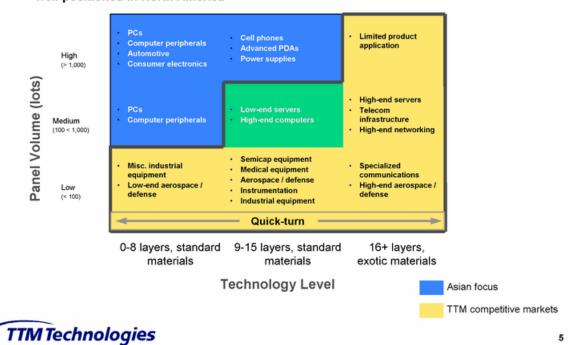
Auto	4.0%
Communication	4.3%
Computing	4.8%
Consumer	4.1%
Industrial/Medical	5.4%
Aerospace/Defense	5.2%
Packaging	7.2%
Total	5.0%

Global PCB End-Market Analysis

Source: Prismark Partners 2008

# Global PCB Competitive Landscape

Advanced technology, quick-turn and aerospace/defense segments are well-positioned in North America



# Recent Trends - Industry

Aerospace/Defense: Remains strong

Quick Turn: Solid

Networking/Communications: Solid

+ High end computing: Steady

+ High Mix: Steady

Raw material pricing: Steady

Technology: Continued growth in sequential

lamination & HDI requirements

Pricing: Steady

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# TTM's Strategy

### Aerospace / Defense

- #1 North America Supplier
- Rigid Flex and speciality PCB products
- Backplane and Subassembly

### Technology

- High performance, technologically complex PCBs
- Advanced manufacturing processes & technology expertise
- Industry-leading average layer count of 20+ at Chippewa Falls facility

# Industry-Leading Execution and Financial Results

### Strong Long-Term Outlook

- Financial Strength

  Focus on operational excellence
- Superior asset management and strong balance sheet
- Successful integration of opportunistic acquisitions

### Time

- Dedicated ultra-short lead time capability (<24 hours available)</li>
- Dedicated, highly flexible, ramp-tovolume production in <10 days</li>
- High-mix complex technology production with standard delivery





Doug Soder – Executive Vice President

# North American PCB Market Overview

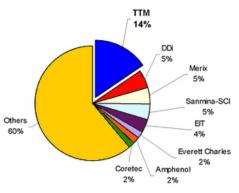
### The \$3.9 billion North American PCB market is highly fragmented

- TTM is the largest PCB company in North America
- Larger, well-capitalized players with focused strategies, significant scale and advanced technology capability are positioned to benefit from on-going industry consolidation
- North American industry capacity has declined significantly since 2000
  - Total number of PCB manufacturers reduced by approximately 50%
  - Only 5 companies have over \$100 million in sales

### **Fragmented North American Market**

# Greater than \$100M TTM Merix EIT DDi Sanmina-SCI 5 > \$100mm 36 \$20 to \$99mm 44 \$10 to \$19mm 309 \$0 to \$9mm Total: 394 PCB Companies

North American Market Share Analysis



Source: FabFile Online estimates



Source: FabFile Online

# U.S. Aerospace/Defense PCB Market

### TTM is the clear leader in the fragmented U.S. defense market



Top Players' Marke	et Share
ттм	22.7%
DDi	5.5%
Pioneer Circuits	4.2%
FTG	3.8%
EIT	3.4%
Top 5	40%
Top 10	51%

Source: Annual sales data from Harvey Miller FabFile 2008



# TTM Global Selling Force

### 153 Total Selling Assets

- 56 Direct Sales Personnel
- 43 Independent Manufacturing Rep Firms
- 46 Technical Sales Support Personnel
- 8 Design Services Personnel

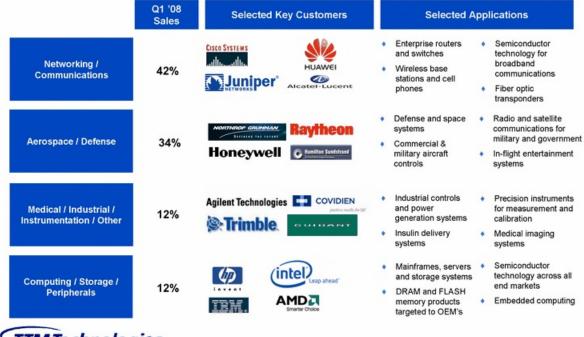
### Structure Facilitates Global Focus on General & Strategic Customers Across All Lines of Business

- Regional Sales Teams
- OEM & EMS Strategic Account Management Teams
  - 15 SAM Teams
- Focused BPA & Commercial PCB Business Development
- Product, Technology & Design Engineering Support Teams



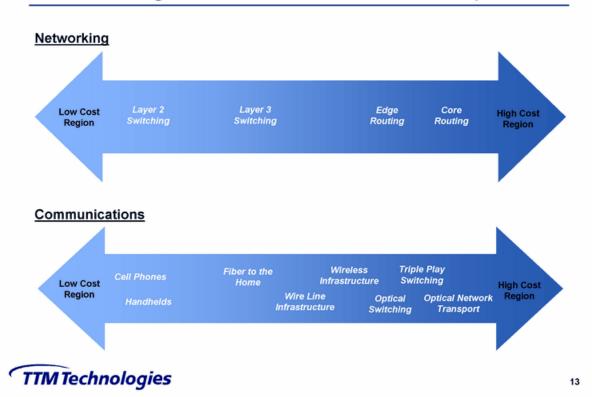
# Key Customers by End Market

### TTM serves approximately 900 active customers across a broad range of end-markets



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# Computing/Storage/Peripherals Landscape

### Computing/Storage/Peripherals





# Medical/Industrial/Instrumentation Landscape

### Large and Disaggregated Customer Set

- Over 400 Active Customers in 2007
  - Average Annual Revenue Per Customer in 2007 was approximately \$200K
  - Only 4 Customers Exceeded Revenue of \$1.0 Million in Q1 2008

### TTM Competitive Strengths for these Customers Include:

- High-Mix / Low Volume; Quick-Turn; IPC Class III
- Product Applications:
  - Medical
    - MRI; Ultrasound; Dental X-ray; Diagnostics Equipment
  - Industrial
    - Electrical Power Control & Management; Power Supply Systems; Radio & Vision Systems
  - Instrumentation
    - Semiconductor Test Equipment; Weather Instrumentation; Laboratory Analysis



# Long-Term Customer Relationships with Industry Leaders

# TTM maintains deep, long-term customer relationships with minimal concentration risk

No customer accounted for more than 8% of 2007 revenues

Customer	% of 2007 Revenues	Customer Relationship (Years)	Industry Sector
CISCO SYSTEMS	7.5	9+	Telecom / Networking
<b>Juni</b> per°	4.9	7+	Telecom / Networking
Raytheon	4.6	21+	Aerospace / Defense
HORTHOP CRUPHAN	3.5	16+	Aerospace / Defense
Honeywell	3.5	31+	Aerospace / Defense
○ Hamilton Sundstrand	3.2	21+	Aerospace / Defense
BAE SYSTEMS	3.1	21+	Aerospace / Defense
<b>(</b> p)	2.7	20+	Computing / Storage / Peripherals
IBM.	2.6	24+	Computing / Storage / Peripherals
Alcatel-Lucent	2.6	20+	Telecom / Networking
Total	38.2		

Average Top 10 Customer relationship: 19+ years





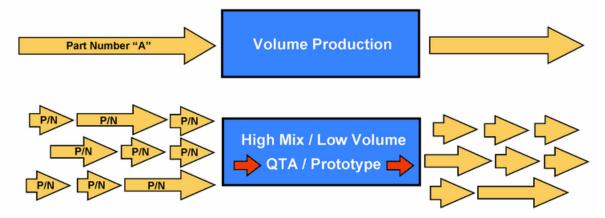
Shane Whiteside - Chief Operating Officer

# PCB Manufacturing Overview

- #1 North American PCB Manufacturer
- Leader in U.S. aerospace/defense market
- Broadest offering of technology
- Market leader in quick-turn
- One stop solution for prototype through production
- Specialized facilities



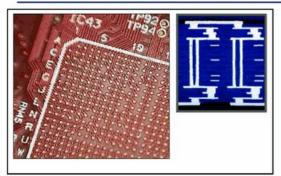
# **Manufacturing Models**

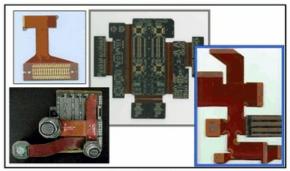


Model	Capital Utilization	Setups/ Changeovers	Human Capital Required	Tooling Capacity	Focus
Volume	High	Low	Low	Low	Materials Cost
High Mix	Medium	High	High	Medium	Fixed Cost Absorption
QTA	Low	High	High	High	On Time Delivery

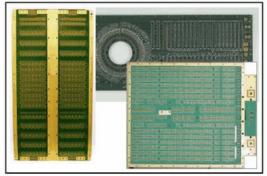


# **Printed Circuit Board Products**

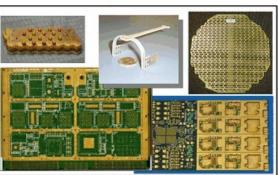




High Density Interconnect (HDI) PCBs



Rigid-Flex PCBs



Backplane PCBs

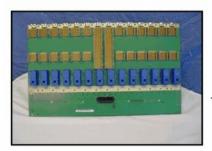
RF PCBs

# **Backplane Assembly Overview**

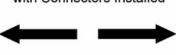
- Leading Market Positions in North America and China
- Limited Competition with EMS Companies
- Product & Service Offering Includes:
  - Backplane & Chassis Assemblies
  - Rigid-Flex Assemblies
  - System Design & Simulation Services
- Strategic Rationale
  - Strengthens TTM Supplier Status with Key Global Customers
  - Presents Significant Growth Opportunities in China
  - Drives Internal PCB Demand
  - Profitable Business with Opportunities for Margin Improvement

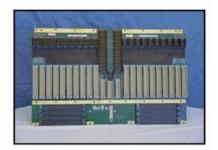


# **Backplane Assembly Products**



Bare Backplane Boards with Connectors Installed







Assembled Backplanes Installed into Enclosures







# **PCB Technology Drivers**

### INDUSTRY DRIVERS

### Signal Speed

 Continued improvements in silicon drive higher signal speeds



### **PCB TECHNOLOGY**

Materials & methods must be developed to allow signals to maintain integrity as speeds increase >3 GHz

### Component Density

 Increased processing power results in components with higher pin counts and smaller in size



High Density Interconnect (HDI) approaches to resolving the interconnection of the semiconductor and the printed circuit board

### Package / System Size

 Demands for small, light-weight products drives smaller electronic packages



Thinner rigid and flexible materials must be developed to reduce the overall thickness of the PCB

### Environmental

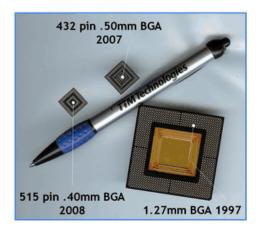
 Recent & evolving standards seek to reduce the amount of harmful materials used in electronic manufacturing

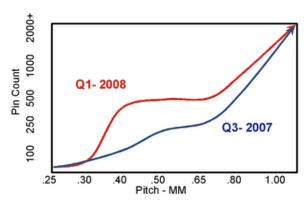


Lead free assembly requires laminates that can withstand higher assembly temperatures



# **Component Density Example**





Source: TTM Technologies

• These components / packages are mounted to the PCBs we build



# **HDI Terminology**

Stacked Vias

Microvia stacked on a buried via

Stacked Microvias

Microvia stacked on microvia



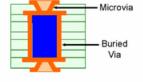
Microvia centerline offset (staggered) from buried via centerline

Staggered Microvias

Microvia centerlines offset (staggered)

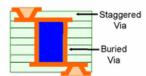
Via in Pad (VIP)

Small vias drilled in the center of a microvia

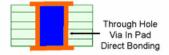
















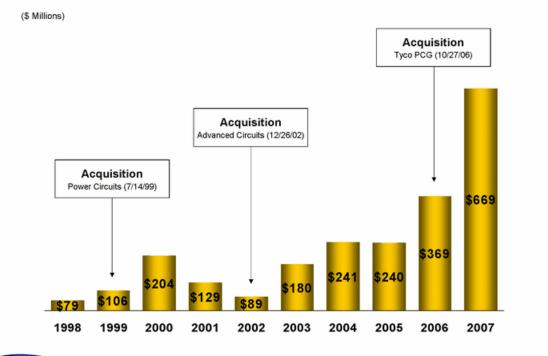
Steven Richards - Chief Financial Officer

### **Convert Overview**

- Total \$175 million @ 3.25% interest rate fixed for life
  - \$155 million base principal amount
  - \$20 million over-allotment (Closed on 5/20/08)
- Conversion premium set at \$15.96, or 1.275 times 5/8/08 closing stock price of \$12.52
- Call spread overlay provides an effective conversion premium of 45 percent up or \$18.15
- No EPS dilution unless stock price exceeds \$18.15
- Classified as senior unsecured long-term debt
- Minimal covenants
- Non-callable for life
- In Q2 2008, one-time hedge unwind costs of \$1.3M and amortization of debt costs of \$1.7M related to the retired debt



# **Annual Sales**



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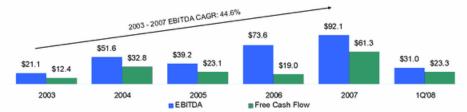
# Historical Revenue, EBITDA & Free Cash Flow

(\$ Millions)

### Revenue



### **EBITDA and Free Cash Flow**



Note: Acquired Tyco PCG on 10/27/06. Find reconciliation to audited financials in Appendix



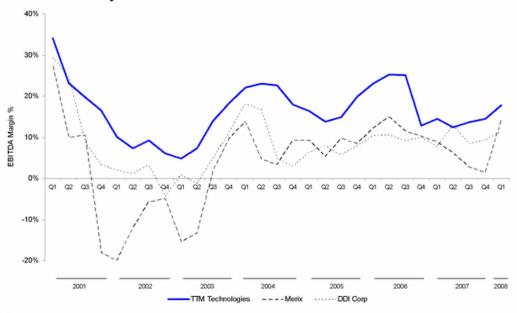
# Quarterly EBITDA and EBITDA Margin



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# **EBITDA Margin Benchmarking**

Relative to its peers, TTM has been more effective at managing through PCB business cycles



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# **Quarterly Results**

(\$ in Millions, except EPS)

		200	6			200	07		2	800
	1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q	1Q	2QE*
Revenue	\$72.7	\$76.7	\$75.8	\$144.1	\$176.9	\$162.0	\$163.1	\$167.5	\$174.1	\$170 - \$177
Gross Profit	\$20.2	\$23.0	\$22.5	\$27.4	\$34.7	\$29.5	\$31.2	\$34.7	\$37.6	
% Margin	28%	30%	30%	19%	20%	18%	19%	21%	22%	19% - 21%
Operating Income	\$13.0	\$15.6	\$15.0	\$11.4	\$17.8	\$13.1	\$15.2	\$17.6	\$24.4	
GAAP Diluted EPS	\$0.21	\$0.25	\$0.25	\$0.12	\$0.20	\$0.15	\$0.19	\$0.28	\$0.34	\$0.20 - \$0.25
Operating Cash Flow	\$10.0	\$10.8	\$11.7	\$0.3	\$28.3	\$13.7	\$14.9	\$17.1	\$26.8	
Free Cash Flow	\$6.6	\$8.6	\$8.7	(\$4.9)	\$24.7	\$10.1	\$12.1	\$14.4	\$23.3	

<sup>\*</sup>Q2 guidance provided April 30, 2008 prior to TTM's convertible note offering on May 8, 2008 Note: Find reconciliation to audited financials in Appendix



# Historical Income Statement

	Fiscal Years Ended December 31,								
(\$ in millions)	2003	2004	2005	2006	2007	3/31/08			
Revenue	\$180.3	\$240.7	\$240.2	\$369.3	\$669.5	\$174.1			
Cost of Goods Sold	145.7	172.1	186.5	276.2	539.3	136.5			
Gross Profit	34.6	68.5	53.8	93.1	130.2	37.6			
Selling and Marketing Expense	10.9	12.0	12.0	16.5	29.8	7.7			
General and Administrative Expenses	11.7	13.2	11.9	19.6	32.7	8.2			
Loss Contingency Accrual	0.0	0.0	2.2	0.0	0.0	0.0			
Amortization of Intangibles	1.2	1.2	1.2	1.8	4.1	1.0			
Restructuring Charges	0.6	0.9	0.0	0.2	0.0	0.0			
Metal Reclamation	0.0	0.0	0.0	0.0	0.0	(3.7)			
Operating Income	10.2	41.2	26.4	55.0	63.6	24.4			
Interest Expense	0.6	0.4	0.2	3.0	10.1	1.8			
Amortization of Debt Issuance Costs	0.1	0.1	0.1	0.4	3.7	0.0			
Interest (Income) and Other	(0.4)	(0.8)	(2.1)	(4.5)	(1.5)	(0.3)			
Income Before Taxes	9.9	41.5	28.3	56.1	51.3	22.9			
Tax Provision (Benefit)	3.9	13.2	(2.5)	21.1	16.6	8.5			
Income Before Extraordinary Items	6.0	28.3	30.8	35.0	34.7	14.4			
Extraordinary Gain	1.5	0.0	0.0	0.0	0.0	0.0			
Net Income	\$7.4	\$28.3	\$30.8	\$35.0	\$34.7	\$14.4			
Growth and Margins									
Revenue Growth	102.6%	33.5%	(0.2%)	53.7%	81.3%				
Gross Margin	19.2%	28.5%	22.4%	25.2%	19.4%	21.6%			
Operating Income Margin	5.7%	17.1%	11.0%	14.9%	9.5%	14.0%			
EBITDA Margin	11.7%	21.4%	16.3%	19.9%	13.8%	17.8%			
Net Income Margin	4.1%	11.8%	12.8%	9.5%	5.2%	8.3%			

Note: Find reconciliation to audited financials in Appendix



# Historical Balance Sheet

(\$ in millions)	December 31, 2006	December 31, 2007	March 31, 2008
Assets:			
Cash, Cash Equivalents and Short-Term Investments	\$70.7	\$18.7	\$32.6
Accounts Receivable	125.4	118.6	118.2
Inventories	67.0	65.7	73.7
Other Current Assets	8.6	16.9	15.1
Total Current Assets	271.7	219.9	239.6
Property, Plant & Equipment	206.7	199.8	202.7
Accumulated Depreciation	(55.9)	(76.1)	(80.9)
Net Fixed Assets	150.9	123.7	121.8
Net Goodwill	115.6	130.1	130.8
Net Intangibles	26.2	22.1	21.2
Other Assets	9.3	3.0	4.0
Total Assets	573.7	498.8	517.4
Liabilities and Equity:			
Current Portion Long-Term Debt	60.7	40.0	43.0
Accounts Payable	49.3	53.6	62.0
Accrued Salaries, Wages and Benefits	24.2	21.6	19.9
Other Accrued Expenses	10.2	5.9	5.8
Income Taxes Payable	0.0	0.0	3.6
Total Current Liabilities	144.4	121.1	134.3
Long-Term Debt, Less Current Portion	140.0	45.0	32.0
Other Long-Term Liabilities, Less Current Portion	2.0	4.1	6.4
Total Liabilities	286.4	170.2	172.7
Total Stockholders' Equity	287.3	328.6	344.7
Total Liabilities and Equity	\$573.7	\$498.8	\$517.4





Kent Alder - Chief Executive Officer and President

### Summary

Leading market positions in attractive segments

- · Largest player in North America with significant size and scale
- #1 in Quick-Turn PCB production and Aerospace & Defense PCB products
- Leadership positions for Advanced technology PCBs, Rigid-Flex and Backplane Assembly products

Integrated manufacturing platform provides onestop solution

- Leading quick-turn platform involves TTM in new product introduction across diverse end markets
- Products/services support all stages of electronic product life cycle engineering services, prototype through volume production
- Focused facility specialization strategy speed, flexibility, technology

Limited competition / high entry barriers

- Difficult business model to replicate
- Significant technology expertise, employee training and investment required
- . Limited threat from Asian competition in quick-turn, high layer-count and defense markets

Leading customers in diverse end markets

- . Large and diversified customer base and end-markets
- Strong relationships with leading OEM and EMS customers
- Long-standing relationships with top customers

Industry-leading financial performance

- Consistent history of strong revenue growth: 39% CAGR from 2003-07
- Profitable business model across cycle; superior margins / operating metrics
- Strong balance sheet & proven history of consistent cash flow generation -- even during protracted downturn from 2001-02

Experienced management team with proven execution track record

- · Seasoned management team led by CEO with 26 years of industry experience
- Focused strategy has provided growth / stability across cycles

Successful M&A Track Record

- Proven ability to identify and integrate successful, accretive acquisitions
- Prior acquisitions have strengthened technology capabilities, expanded customer relationships, diversified end-market exposure and enhanced earnings





Non-GAAP supplemental information

# Annual EBITDA and FCF reconciliation

	Fiscal Years Ended December 31,										
(\$ in millions)	2003	2004	2005	2006	2007						
Revenue	\$180.3	\$240.7	\$240.2	\$369.3	\$669.5						
Net income	\$7.5	\$28.3	\$30.9	\$35.1	\$34.7						
Add back items:											
Income taxes	3.9	13.2	(2.5)	21.0	16.6						
Interest expense	0.7	0.5	0.2	3.4	13.8						
Depreciation expense	7.7	8.2	9.3	12.2	22.8						
Amortization of Intangibles	1.3	1.3	1.3	1.9	4.2						
Total	\$13.6	\$23.2	\$8.3	\$38.5	\$57.4						
EBITDA	\$21.1	\$51.6	\$39.2	\$73.6	\$92.1						
EBITDA Margin	11.7%	21.4%	16.3%	19.9%	13.8%						
		Fiscal Year	s Ended Decem	ber 31,							
(\$ in millions)	2003	2004	2005	2006	2007						
Operating cash flow	\$18.6	\$48.8	\$31.0	\$32.8	\$74.0						
Less: Capital expenditures	(6.2)	(16.0)	(8.0)	(13.7)	(12.7)						

Note: This information provides a reconciliation of EBITA/EBITDA to the financial information in our consolidated statements of operations

"EBITDA" means earnings before interest expense, income taxes, depreciation and amortization. "EBITDA" means earnings before interest expense, income taxes and amortization. "We present EBITDA / EBITA to enhance the understanding of our operating results. EBITDA / EBITA is a key measure we use to evaluate our operations. In addition, we provide our EBITDA / EBITA because we believe that investors and securities analysis will find EBITDA / EBITA to be addition, operating performance and comparing our operating performance with that of similar companies that have efferent capital structures and for evaluating our ability to meet our future debt service, capital expenditures, and working capital requirements. However, EBITDA / EBITA abould not be considered as an alternative to an alternative to not income as a measure of operating results in accordance with accounting principles generally accepted in the United States of America.

\$12.4

\$32.8

\$23.1

\$19.0



Free cash flow

\$61.3

# Quarterly EBITDA and FCF reconciliation

	2005				2006			2007				2008	
(\$ in millions)	1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q	1Q
Revenue	\$58.9	\$57.2	\$61.0	\$63.1	\$72.7	\$76.7	\$75.8	\$144.2	\$176.9	\$162.0	\$163.1	\$167.5	\$174.1
Net income	\$4.5	\$3.3	\$4.1	\$19.0	\$8.8	\$10.6	\$10.5	\$5.2	\$8.5	\$6.2	\$8.2	\$11.8	\$14.4
Add back items:													
Income taxes	2.7	2.0	2.4	(9.6)	5.1	6.1	5.9	4.1	5.0	3.7	4.7	3.2	8.5
Interest expense	0.1	0.0	0.0	0.2	0.1	0.0	0.0	3.3	5.1	3.4	2.6	2.7	1.8
Depreciation expense	2.1	2.3	2.3	2.6	2.4	2.4	2.3	5.1	5.9	5.7	5.6	5.6	5.3
Amortization of Intangibles	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.9	1.0	1.1	1.1	1.1	1.0
Total	\$5.2	\$4.6	\$5.0	(\$6.5)	\$7.9	\$8.9	\$8.5	\$13.3	\$17.0	\$13.9	\$14.0	\$12.6	\$16.6
EBITDA	\$9.7	\$7.9	\$9.1	\$12.5	\$16.7	\$19.4	\$19.0	\$18.5	\$25.5	\$20.1	\$22.2	\$24.4	\$31.0
EBITDA Margin	16.4%	13.8%	14.9%	19.8%	22.9%	25.3%	25.1%	12.8%	14.4%	12.4%	13.6%	14.6%	17.8%
						20	06			20	07		2008
(\$ in millions)					1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q	1Q

 Ks in millions)
 1Q
 2Q
 3Q
 4Q
 1Q
 2Q
 2Q
 3Q
 4Q
 1Q
 2Q
 2Q
 2Q
 2Q
 2Q
 2Q

Note: This information provides a reconciliation of EBITA/EBITDA to the financial information in our consolidated statements of operations

"EBITDA" means earnings before interest expense, income taxes, depreciation and amortization. "EBITA" means earnings before interest expense, income taxes and amortization. We present EBITDA / EBITA to enhance the understanding of our operating results. EBITDA / EBITA is a key measure we use to evaluate our operations. In addition, we provide our EBITDA / EBITA because we believe that investors and securities analysts will find EBITDA / EBITA to be actual termination operating performance and comparing our operating performance with that of similar companies that have different capital structures and for evaluating our operating performance and comparing our operating performance with that of similar companies that have different capital structures and for evaluating our object of the comparing our operating performance with the comparing our operating performance and comparing our operating performance with the comparing our operating performance with the comparing our operating performance and the comparing our operating performance with the comparing our operating performance and the comparing ou



# TTM Technologies, Inc.

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